



## 2x64Kx16 SRAM, DSP Memory Solution

### FEATURES

- Access Times of 10, 12 and 15ns
- DSP Memory Solution
  - Texas Instruments TMS320C5x
- Packaging:
  - 74 pin BGA, JEDEC MO-151
- 3.3V Operating Supply Voltage
- Single Write Control and Output Enable Lines
- One Chip Enable Line per Memory Bank
- 50% Space Savings vs. Monolithic TSOPs
- Upgrade Path Available in Same Footprint
- Multiple Vcc and Vss Pins
- Reduced Inductance and Capacitance

### DESCRIPTION

The EDI8L21665VxxBC is a 3.3V, 2x64Kx16 SRAM constructed with two 64Kx16 die mounted on a multi-layer laminate substrate. The device is packaged in a 74 lead, 15mm by 15mm, BGA.

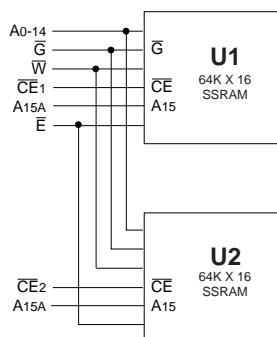
Operating with a 3.3V power supply and with access times as fast as 10ns, the device allows the user to develop a fast external memory for Texas Instruments' TMS320C5x DSP.

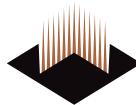
The device consists of two separate banks of 64Kx16 of memory. Each bank has a separate Chip Enable pin and higher order address select pin. Bank 'A' is controlled using CE1\ and A15A. Bank 'B' is controlled using CE2\ and A15B. The two banks have common I/Os (DQ0-15) and control lines (WE\, E\ and G\). E\ connects to the mstrb\ pin of the C54x DSPs and is required for write and read timing control.

### PIN CONFIGURATION

	1	2	3	4	5	6	7	8	9	10	11	
A	Vss	Vcc	Vcc	DQ15	DQ14	Vcc	DQ13	DQ11	DQ9	DQ8	NC	
B	Vss	Vcc	Vcc	Vss	Vss	Vcc	DQ12	DQ10	DQ4	Vcc	Vcc	
C	Vss	Vss				Vcc			Vss	Vcc		
D	Vss	Vss							Vss	Vcc		
E	Vss	Vss							Vss	Vcc		
F	A15A	CE1							DQ3	DQ7		
G	E	W							DQ5	DQ0		
H	Vss	CE2							DQ6	DQ1		
I	Vss	A14			Vcc				DQ2	NC		
J	Vss	A12	Vcc	A10	A8	Vss	A6	A4	A2	A0	G	
K	A15B	A13	Vcc	A11	A9	Vss	A7	Vss	A5	A3	A1	
	1	2	3	4	5	6	7	8	9	10	11	

### BLOCK DIAGRAM





## PIN DESCRIPTIONS

Pin	Symbol	Type	Description
	A0-14	Input	Addresses
	A15A	Input	Addresses: A15 on Bank 'A' of memory
	A15B	Input	Addresses: A15 on Bank 'B' of memory
	W	Input	Write Enable: This active LOW input allows a full 16-bit WRITE to occur.
	CE1	Input	Chip Enable: This active LOW input is used to enable the 'A' Bank of the device.
	CE2	Input	Chip Enable: This active LOW input is used to enable the 'B' Bank of the device.
	G	Input	Output Enable: This active LOW asynchronous input enables the data output drivers.
Various	DQ0-15	Input/Output	Data Inputs/Outputs
Various	Vcc	Supply	Core power supply: +3.3V -5%/+10%
Various	Vss	Ground	Ground
	E	Input	Enable, This active LOW input controls Write and Read Timing

## ABSOLUTE MAXIMUM RATINGS\*

Voltage on Vcc Supply Relative to Vss	-0.5V to 4.6V
V <sub>IN</sub>	-0.5V to V <sub>CC</sub> +0.5V
Storage Temperature	-55°C to +125°C
Junction Temperature	+125°C
Power Dissipation	3 Watts
Short Circuit Output Current (per I/O)	50 mA

\* Stress greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions greater than those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

## RECOMMENDED OPERATING CONDITIONS

Description	Symbol	Min	Max	Unit
Input High Voltage	V <sub>IH</sub>	2.2	V <sub>CC</sub> +0.5	V
Input Low Voltage	V <sub>IL</sub>	-0.3	0.8	V
Supply Voltage	V <sub>CC</sub>	3.0	3.6	V

CAPACITANCE  
(f = 1MHz, V<sub>IN</sub> = V<sub>CC</sub> or V<sub>SS</sub>)

Parameter	Symbol	Max	Unit
Address Lines	C <sub>A</sub>	8	pF
Data Lines	C <sub>D/Q</sub>	17	pF
Control Lines	C <sub>C</sub>	15	pF

## DC ELECTRICAL CHARACTERISTICS

(f = 1MHz, V<sub>IN</sub> = V<sub>CC</sub> or V<sub>SS</sub>)

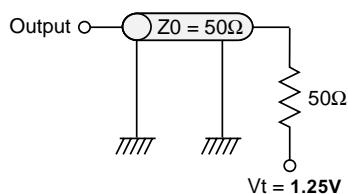
Parameter	Symbol	Conditions	Min	Max	Units
Power Supply Current: Operating	I <sub>CC1</sub>	Device Selected; all inputs ≤ V <sub>IL</sub> or ≥ V <sub>IH</sub> ; -10ns cycle time ≥ t <sub>CK</sub> MIN; -12ns V <sub>CC</sub> = MAX; outputs open -15ns	380	360	mA
CMOS Standby	I <sub>SB2</sub>	Device deselected; V <sub>CC</sub> = MAX; all inputs ≤ V <sub>SS</sub> +0.2 or ≥ V <sub>CC</sub> -0.2; all inputs static; CLK frequency = 0	60	60	mA
TTL Standby	I <sub>SB3</sub>	Device deselected; all inputs ≤ V <sub>IL</sub> or ≥ V <sub>IH</sub> ; all inputs static; V <sub>CC</sub> = MAX; CLK frequency = 0	120	120	mA
Input Leakage Current	I <sub>LI</sub>	0V ≤ V <sub>IN</sub> ≤ V <sub>CC</sub>	-5	5	µA
Output Leakage Current	I <sub>LO</sub>	Output(s) disabled, 0V ≤ V <sub>OUT</sub> ≤ V <sub>CC</sub>	-5	5	µA
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -4.0mA	2.4	2.4	V
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 8.0mA	0.4	0.4	V



## AC ELECTRICAL CHARACTERISTICS

Read Cycle	Symbol	10ns		12ns		15ns		Units
		Min	Max	Min	Max	Min	Max	
Read Cycle Time	tAVAV	10		12		15		ns
Address Access Time	tAVQV		10		12		15	ns
Chip Enable Access	tELQV		10		12		15	ns
Output Hold from Address Change	tAVQX	3		4		4		ns
Chip Enable to Output in Low-Z	tELQX	3		4		4		ns
Chip Disable to Output in High-Z	tEHQZ		5		6		7	ns
Output Enable access time	tGLQV		5		6		7	ns
Output Enable to Output in Low-Z	tGLQX	0		0		0		ns
Output Disable to Output in High-Z	tGHQZ		5		6		7	ns
<b>Write Cycle</b>								
Write Cycle Time	tAVAV	10		12		15		ns
Chip Enable to End of Write	tELWH	8		8		9		ns
Address valid to End of Write, with $\bar{G}$ HIGH	tAVGHW	8		8		9		ns
Address Setup Time	tAVWL	0		0		0		ns
Address Hold from End of Write	tAVWH	8		8		10		ns
Write Pulse Width	tWLWH	10		10		11		ns
Write Pulse Width, with $\bar{G}$ HIGH	tWLGHW	8		8		9		ns
Data Setup Time	tdVWH	6		6		7		ns
Data Hold Time	tWHDX	0		0		0		ns
Write Disable to Output in Low-Z	tWHQX	3		4		5		ns
Write Enable to Output in High-Z	twLQZ		5		6		7	ns

## AC TEST CIRCUIT



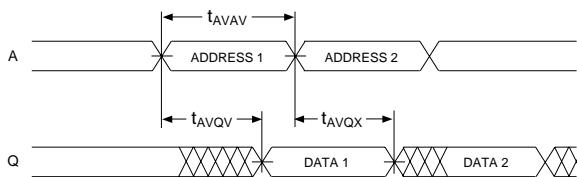
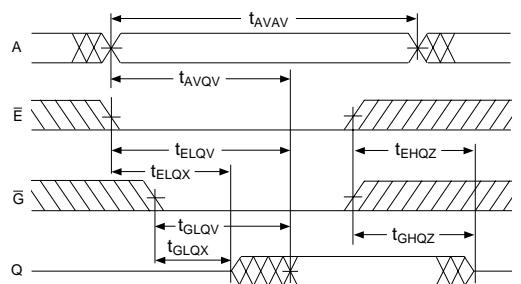
AC Output Load Equivalent

## AC TEST CONDITIONS

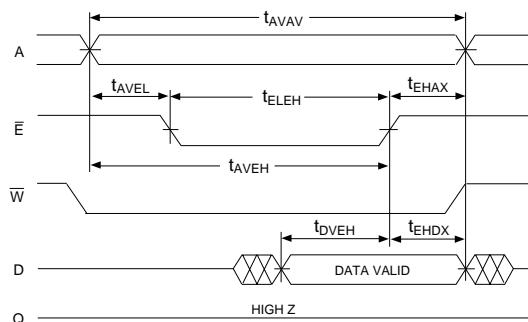
Parameter	I/O	Unit
Input Pulse Levels	V <sub>ss</sub> to 3.0	V
Input Rise and Fall Times (max)	1.5	ns
Input and Output Timing Levels	1.5	V
Output Load	See figure, at left	



## READ CYCLE TIMING DIAGRAMS

READ CYCLE 1 ( $\bar{W}$  HIGH;  $\bar{G}$ ,  $\bar{E}$  LOW)READ CYCLE 2 ( $\bar{W}$  HIGH)

## WRITE CYCLE TIMING DIAGRAM

WRITE CYCLE 2,  $\bar{E}$  CONTROLLED

**NOTES:** All Writes are  $\bar{E}$  controlled when connected to the TMS320C54X.  $\bar{E}$  is connected to  $\overline{\text{MSTRB}}$  and  $\bar{W}$  is connected to  $R/\bar{W}$  of the TMS320C54X.

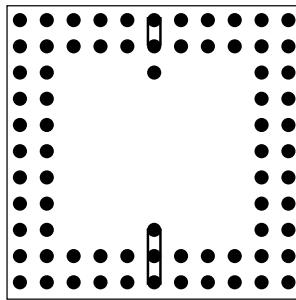
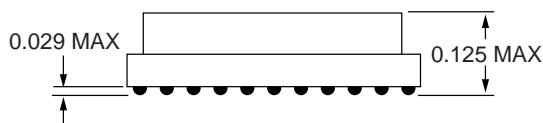
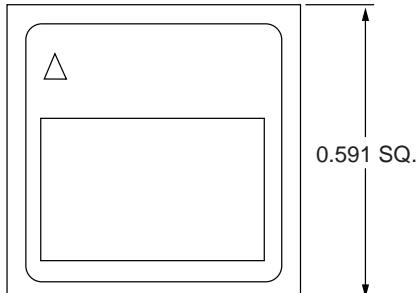
**ORDERING INFORMATION**

Commercial Temperature Range (0°C to +70°C)

Part Number	Speed (ns)	Package No.
EDI8L21665V10BC	10	428
EDI8L21665V12BC	12	428
EDI8L21665V15BC	15	428

Industrial Temperature Range (-40°C to +85°C)

Part Number	Speed (ns)	Package No.
EDI8L21665V15BI	15	428

**PACKAGE DESCRIPTION: 74 PIN BGA****PACKAGE NO. 428****THERMAL PACKAGE  
PERFORMANCE:** $\theta_{JA} = 28^\circ\text{C/Watt}$  (Natural Connection) $\theta_{JB} = 4^\circ\text{C/Watt}$ 

ALL DIMENSIONS ARE IN INCHES